

POWER DISSIPATION (SOT-89-5)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

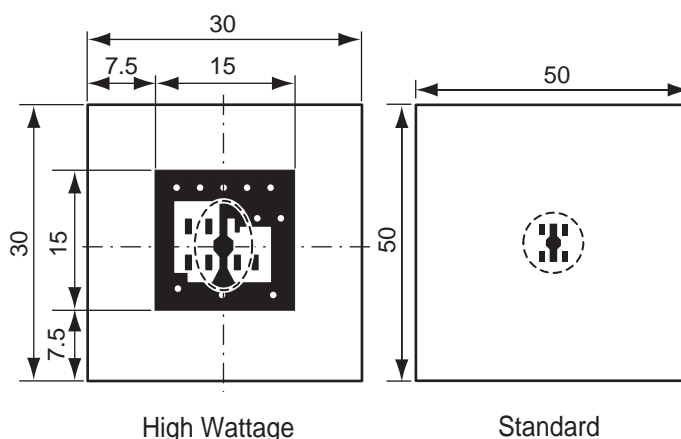
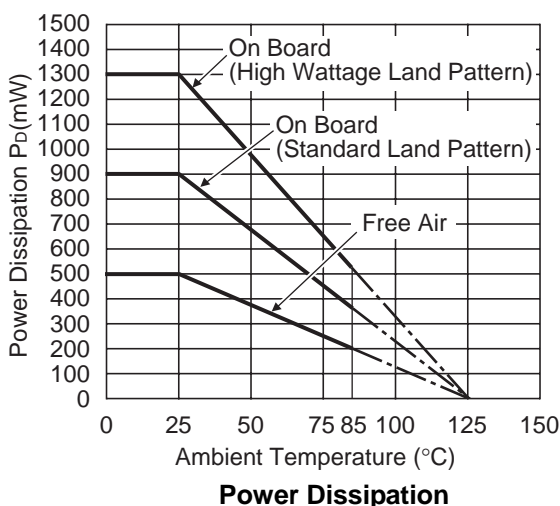
Measurement Conditions

	High Wattage Land Pattern	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)	Glass cloth epoxy plastic (Double sided)
Board Dimensions	30mm × 30mm × 1.6mm	50mm × 50mm × 1.6mm
Copper Ratio	Top side : Approx. 20% , Back side : Approx. 100%	Top side : Approx. 10% , Back side : Approx. 100%
Through-hole	φ0.85mm × 10pcs	-

Measurement Result

($T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$)

	High Wattage Land Pattern	Standard Land Pattern	Free Air
Power Dissipation	1300mW	900mW	500mW
Thermal Resistance	77°C/W	111°C/W	200°C/W



Measurement Board Pattern

○ IC Mount Area (Unit : mm)

RECOMMENDED LAND PATTERN (SOT-89-5)

